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Modular Rackmount Enclosure Allows Mix of 3U and 6U Segments

Waterloo, Ontario — May 23, 2018 – Pixus Technologies, a provider of embedded computing and enclosure solutions, now offers modular subrack/enclosure configurations that facilitate a mix of 6U boards and 3U boards to be used in the same enclosure. The segmentation also allows the use of dual 3U segments.

The Pixus modular 19" rackmount enclosures have been used in various systems to provide a 2nd set of 3U boards to be stacked above another row of 3U boards. The designs include versions in OpenVPX, CompactPCI, and custom backplane architectures. Pixus also offers specialized rugged rails for the high insertion forces of 6U OpenVPX. The company has additionally applied the hybrid 3U/6U approach for horizontal-mount designs. For example, a 1U chassis can facilitate one each of the two board sizes.

Pixus provides subracks and electronics enclosures for various applications, including Industrial, Energy, Communications, Mil/Aero, Medical, Transportation, Research/Physics, and other markets. The company also provides backplanes, chassis platforms, and components for high-performance embedded computing systems.

About Pixus Technologies

Leveraging over 20 years of innovative standard products, the Pixus team is comprised of industry experts in electronics packaging. Founded in 2009 by senior management from Kaparel Corporation, a Rittal company, Pixus Technologies' embedded backplanes and systems are focused primarily on ATCA, OpenVPX, MicroTCA, and custom designs. Pixus also has an extensive offering of VME-based and cPCI-based solutions. In May 2011, Pixus Technologies became the sole authorized North and South American supplier of the electronic packaging products previously offered by Kaparel Corporation and Rittal.